

IN THE SPECIFICATION:

Page 6, first and second full paragraphs, please amend as follows:

To solve the above-mentioned problem, the invention of ~~claim 1~~ is a surface-mount SAW device which comprises: a mounting substrate composed of an insulating substrate, external electrodes mounted on the underside of said insulating substrate for surface mounting use, and conductor traces arranged on the top of said insulating substrate and connected to said external electrodes; a SAW chip provided with a piezoelectric substrate, an IDT electrode formed on one surface of said piezoelectric substrate, and connection pads connected to said conductor traces via conductor bumps; sealing resin layer coated all over the outer surface of said flip-chip mounted SAW chip and down to the top surface of the mounting substrate to form an airtight space between said IDT electrode and said mounting substrate; in which the crystal structure of the piezoelectric substrate belongs to any one of point groups  $C_1$ ,  $C_2$ ,  $C_3$ ,  $C_{2v}$ ,  $C_4$ ,  $C_{4v}$ ,  $C_3$ ,  $C_{3v}$ ,  $C_6$  and  $C_{6v}$  in terms of Schoenflies symbols, which is characterized in that charging of the sealing resin layer is suppressed by increasing the conductivity of said piezoelectric substrate.

The invention of ~~claim 2 is the device of claim 1 which~~ is further characterized in that the conductivity of said piezoelectric substrate is increased by heating an oxidizable element while holding it in contact with said piezoelectric substrate.

Page 7, first and second full paragraphs, please amend as follows:

The invention of ~~claim 3 is the device of claim 1 which~~ is still further characterized in that at least one of such metals as Fe, Zr, Al, Cr, Mn, Rh, Cu, V, W, U and Sn is contained as an impurity in said piezoelectric substrate to provide increased conductivity of said piezoelectric substrate.

The invention of ~~claim 4 is the device of any one of claims 1 to 3 which~~ is also characterized in that said piezoelectric substrate is made of  $\text{LiTaO}_3$ .

Paragraph bridging pages 7 and 8, please amend as follows:

The invention of ~~claim 5~~ is further a surface-mount SAW device which comprises: a mounting substrate composed of an insulating substrate, external electrodes mounted on the underside of said insulating substrate for surface mounting use, and conductor traces arranged on the top of said insulating substrate and connected to said external electrodes; a SAW chip provided with a piezoelectric substrate, an IDT electrode formed on one surface of said piezoelectric substrate, and connection pads connected to said conductor traces via conductor bumps; sealing resin layer coated all over the outer surface of said flip-chip mounted SAW chip and down to the top of the mounting substrate to form an airtight space between said IDT electrode and said mounting substrate, in which the crystal structure of the piezoelectric substrate belongs to any one of point groups  $C_1$ ,  $C_2$ ,  $C_3$ ,  $C_{2v}$ ,  $C_4$ ,  $C_{4v}$ ,  $C_3$ ,  $C_{3v}$ ,  $C_6$  and  $C_{6v}$  in terms of Schoenflies symbols, which is characterized in that: said sealing resin layer has a relative dielectric constant of 3.2 or below and a volume resistivity of  $1 \times 10^{16} \Omega\text{-cm}$  or below; the thickness H of the sealing resin layer on the top surface of said SAW chip is 0.02 mm or above; and the conductivity of said piezoelectric substrate is increased to suppress charging of the sealing resin layer.